

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	ELECTRICAL PACKAGE STRUCTURE INCLUDING CHIP WITH POLYMER THEREON
Application Type : regular, utility Attorney Docket Number : 13365-US-PA	
Correspondence address: Customer Number: 31561 	
Inventors Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: TW Name prefix: Mr. Given Name: Kai-Kuang Family Name: Ho Residence: City of Residence: Hsinchu City Country of Residence: TW Address-1 of Mailing Address: 18F-4, No. 17, Lane 175, Wuling Rd. Address-2 of Mailing Address: City of Mailing Address: Hsinchu City State of Mailing Address: Postal Code of Mailing Address: 300 Country of Mailing Address: TW Phone: Fax: E-mail: <u>Inventor 2:</u> Applicant Authority Type: Inventor Citizenship: TW Name prefix: Mr. Given Name: Kuo-Ming Family Name: Chen	

Residence:

City of Residence: Hsinchu County

Country of Residence: TW

Address-1 of Mailing Address: No. 16-1, Dalin Village, Beipu Township

Address-2 of Mailing Address:

City of Mailing Address: Hsinchu County

State of Mailing Address:

Postal Code of Mailing Address: 314

Country of Mailing Address: TW

Phone:

Fax:

E-mail:

Attorney Information:

practitioner(s) at Customer Number:

31561



as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.